

Category	Capability	Details
Board Size	Min (pcs)	1+0.5mm
	Max (Pnl Size)	250*1200mm
Base Material Thickness		0.06--0.3mm
Board Thickness		0.1-0.5mm
Base Copper Thickness		1/30Z--20Z
PTH Hole Wall Copper Thickness		8-20µm
Blind Hole Filling Capacity Aspect Ratio (Hole Size: Hole Depth)		01:10:00
Blind Hole Filling Capacity (Hole Size)		50-150µm
Single Line Impedance Tolerance		±10%
Differential Impedance Tolerance		±10%
Min Track/Spacing (Double Layers Board)	Surface Copper Thickness : 8-14µm	40/40 µm
	Surface Copper Thickness : 15-20µm	45/45 µm
	Surface Copper Thickness : 21-30µm	55/55 µm
	Surface Copper Thickness : 31-40µm	75/75 µm
	Surface Copper Thickness : ≥40µm	80/80 µm
Line Width Tolerance	Line Width ≤ 0.050mm	±0.02mm
	0.05mm < Line Width ≤ 0.15mm	±20%
	Line Width > 0.150mm	±10%
Silkscreen	Silkscreen Character Min Width/Spacing	4mil
Solder Mask	Green Solder Mask Thickness Range	10~30 µm
Related Capacity	Dimension Tolerance from Line Edge to Plate Edge	±0.25 mm